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(12) **United States Design Patent**
Wu et al.

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(45) **Date of Patent:** **** Nov. 24, 2009**

(54) **HEAT DISSIPATION DEVICE**

2009/0009969 A1* 1/2009 Chu 361/700
2009/0056918 A1* 3/2009 Li et al. 165/104.33

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* cited by examiner

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(**) Term: **14 Years**

(57) **CLAIM**

(21) Appl. No.: **29/324,573**

The ornamental design for a heat dissipation device, as shown and described.

(22) Filed: **Sep. 15, 2008**

DESCRIPTION

(51) **LOC (9) Cl.** **13-03**

FIG. 1 is a perspective view of a heat dissipation device showing our new design.

(52) **U.S. Cl.** **D13/179**

FIG. 2 is a front elevational view thereof.

(58) **Field of Classification Search** D13/179;
165/80.3, 104.33, 151, 122, 185; 257/706,
257/707, 718–722; 361/687, 695, 697, 700,
361/702, 704, 709, 710, 711, 719

FIG. 3 is a rear elevational view thereof.

FIG. 4 is a left-side, elevational view thereof.

See application file for complete search history.

FIG. 5 is a right-side, elevational view thereof.

FIG. 6 is a top plan view thereof; and,

FIG. 7 is a bottom plan view thereof.

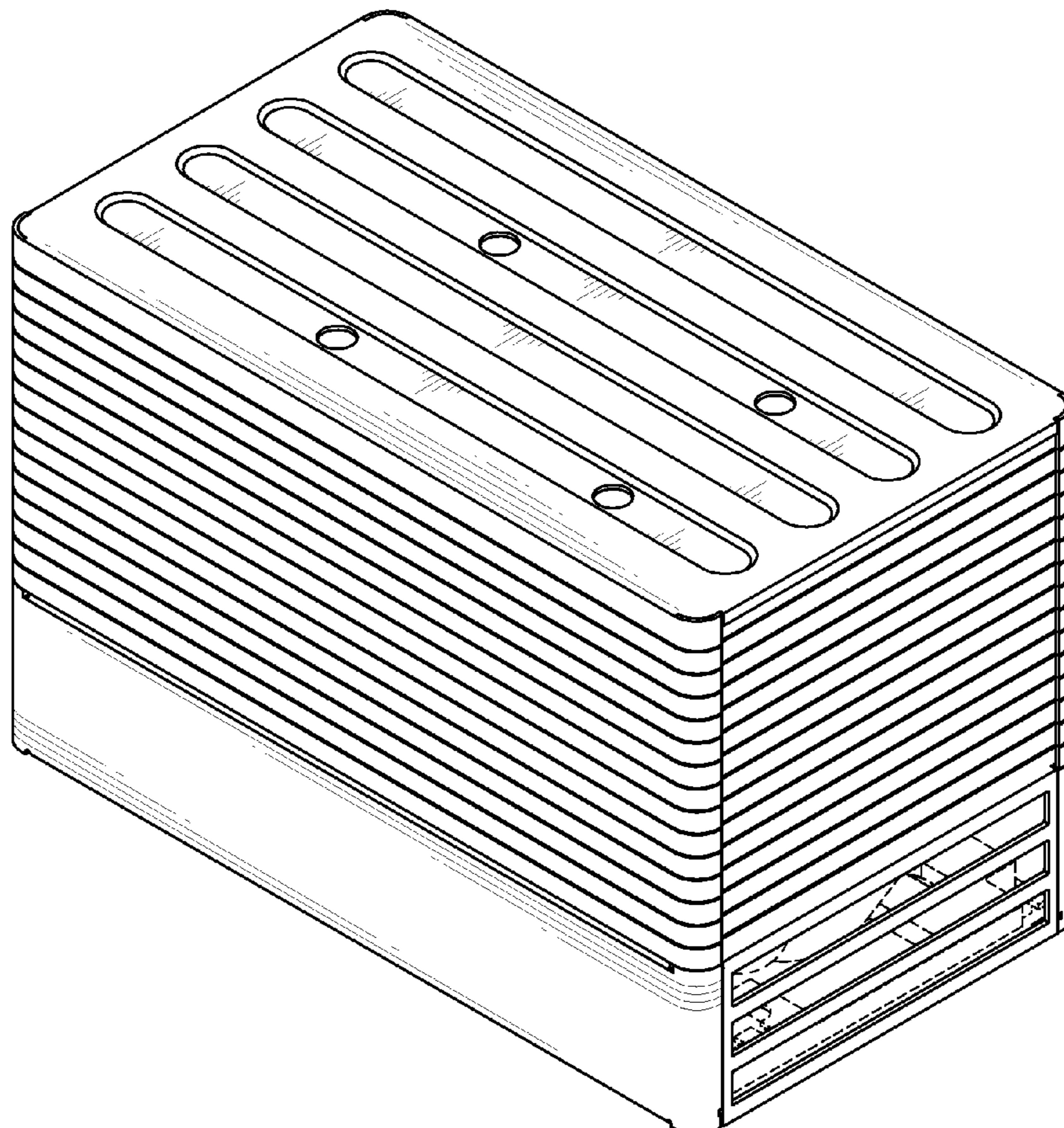
(56) **References Cited**

The broken lines shown in the figures are included for the purpose of illustrating portions of the heat dissipation device that form no part of the claimed design.

U.S. PATENT DOCUMENTS

D475,354 S * 6/2003 Wang D13/179
2005/0133199 A1* 6/2005 Lo 165/80.3
2007/0095508 A1* 5/2007 Xia et al. 165/104.33
2007/0295488 A1* 12/2007 Fielding et al. 165/104.33
2008/0017350 A1* 1/2008 Hwang et al. 165/80.3

1 Claim, 7 Drawing Sheets



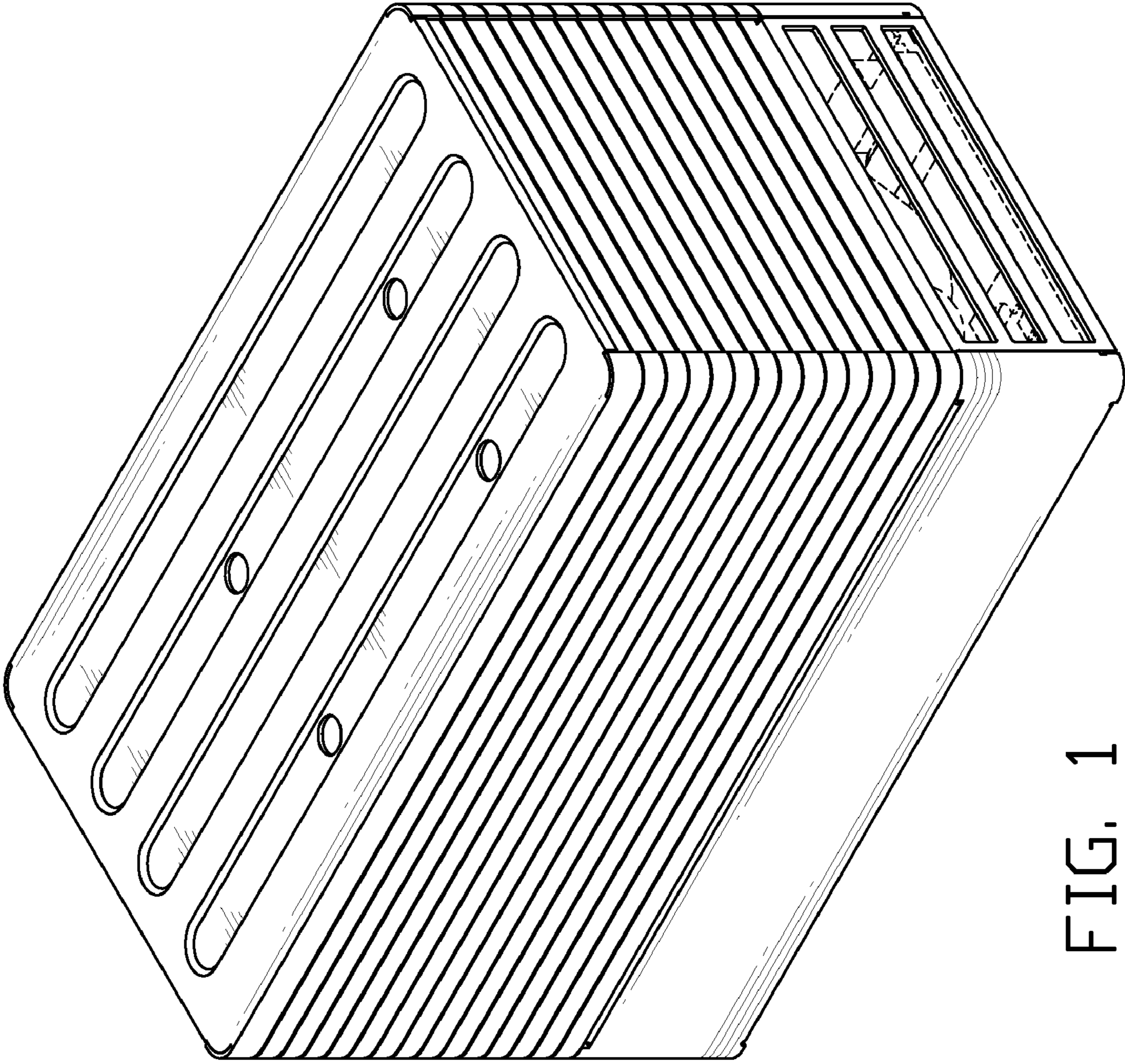


FIG. 1

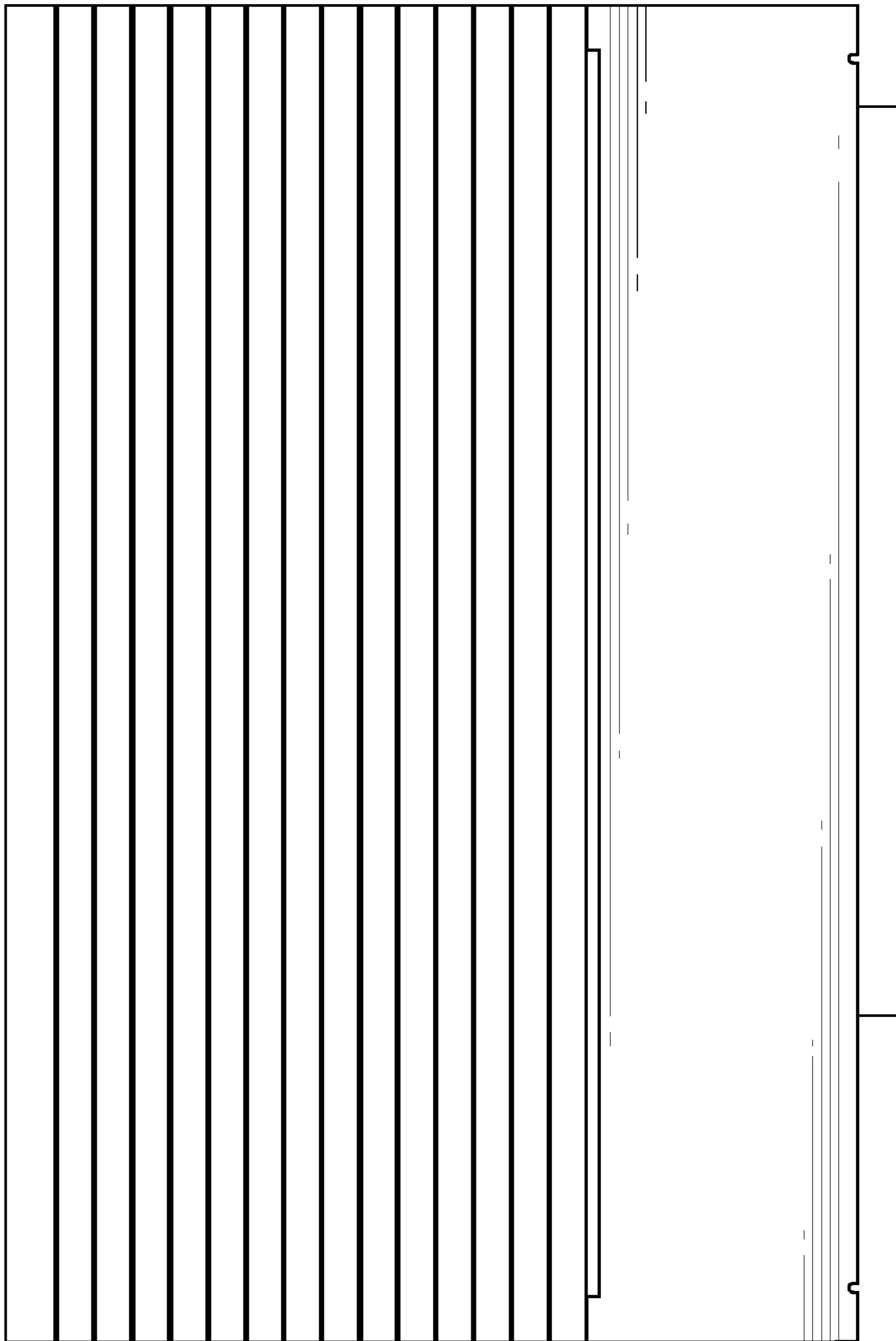


FIG. 2

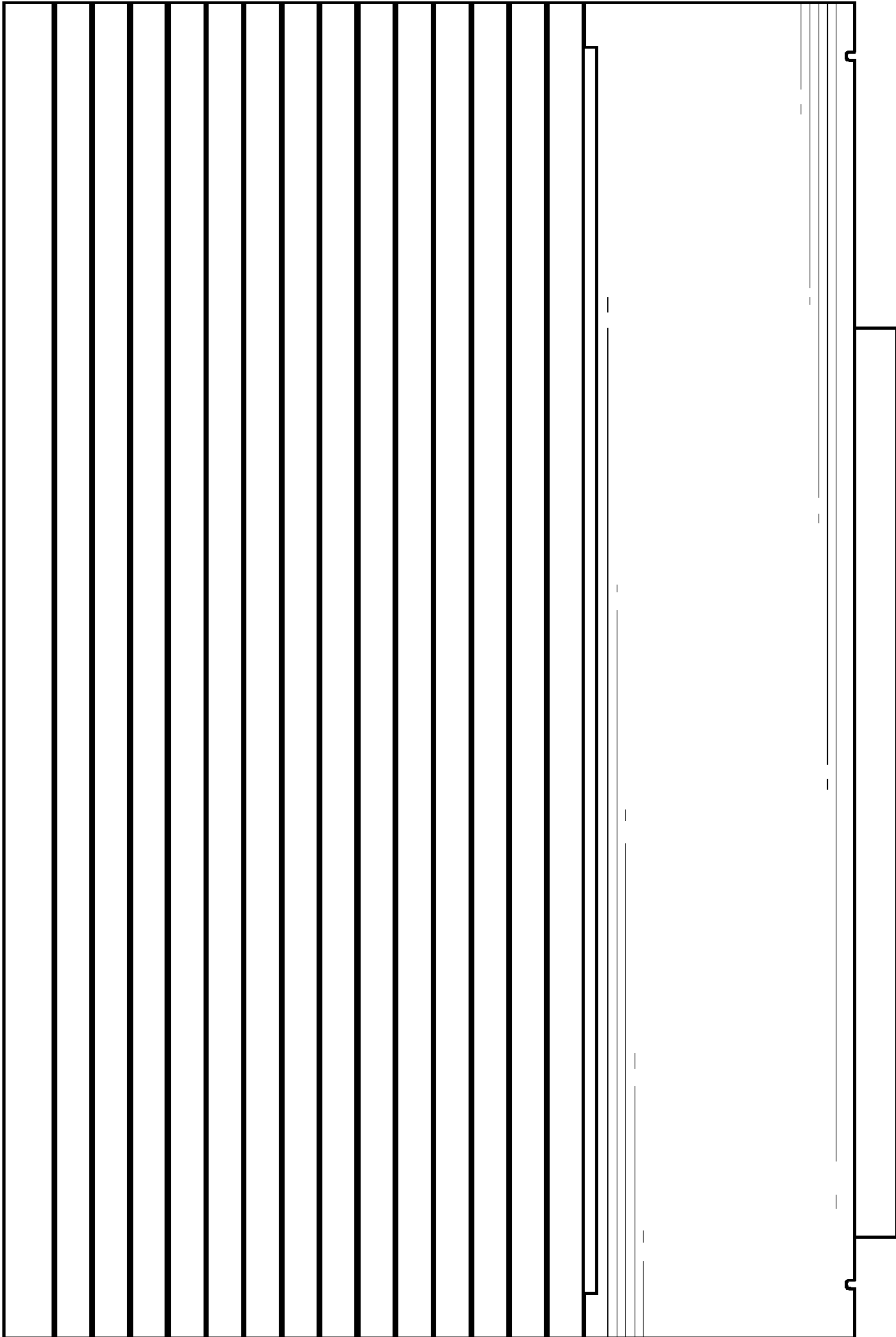


FIG. 3

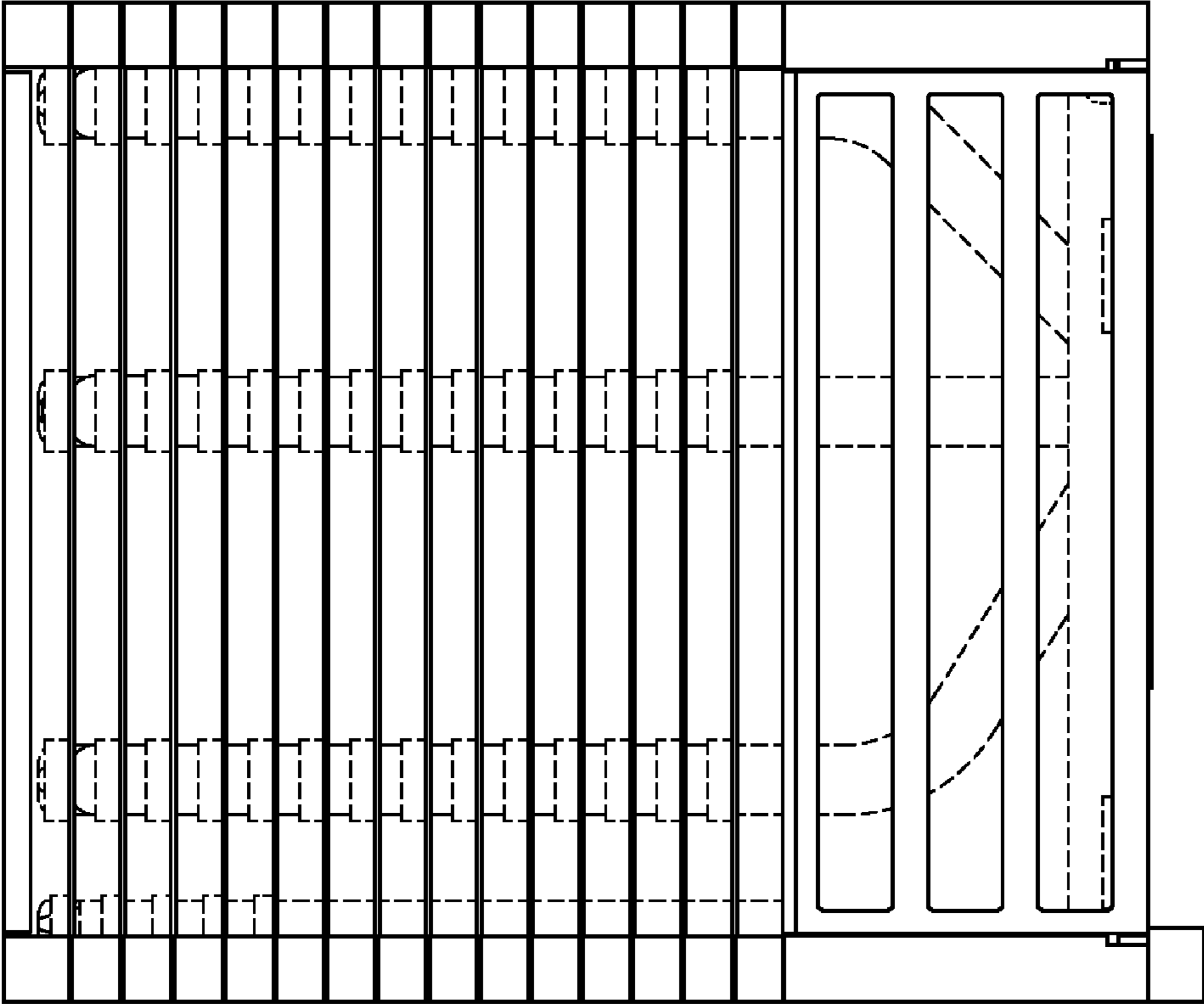


FIG. 4

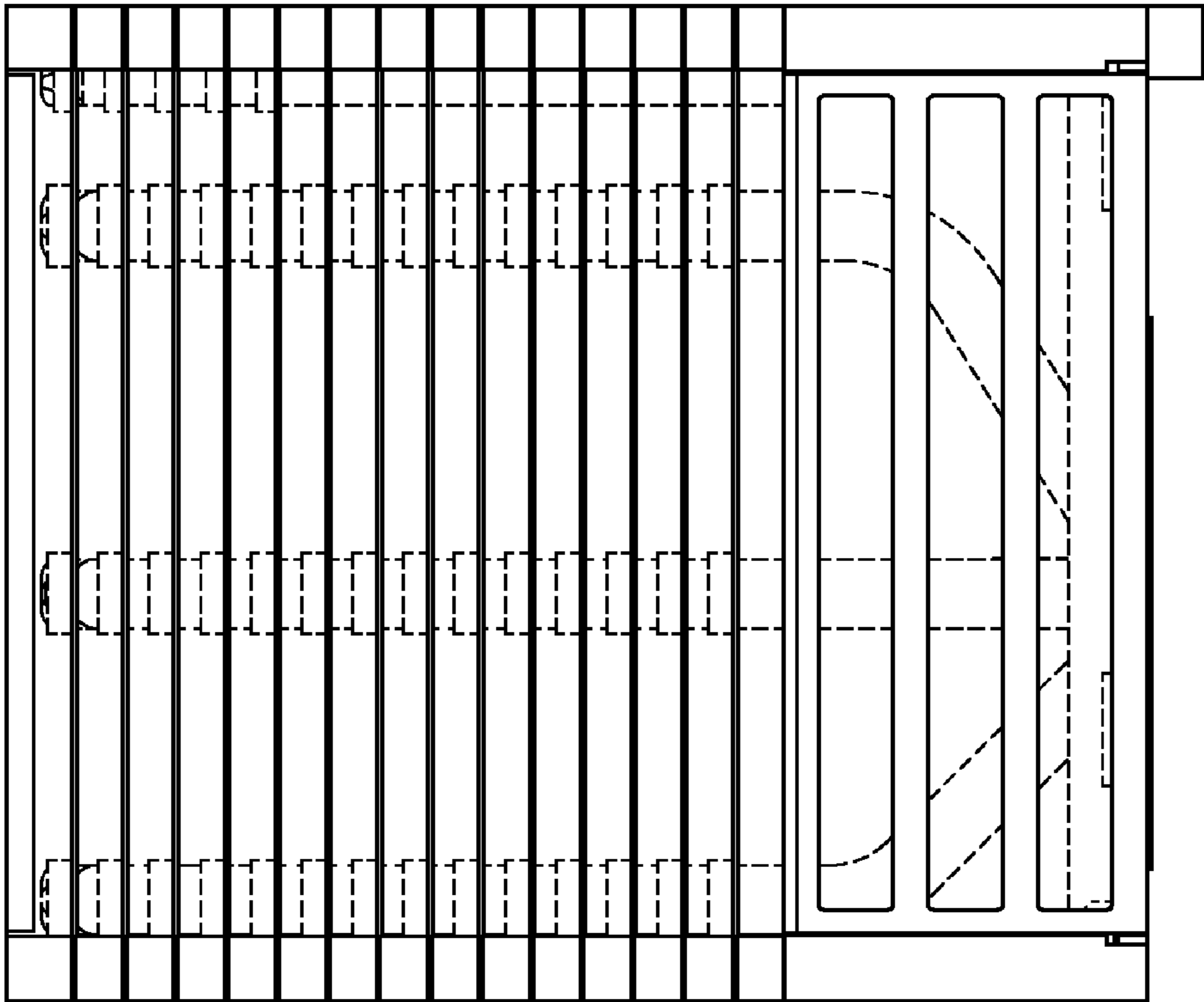


FIG. 5

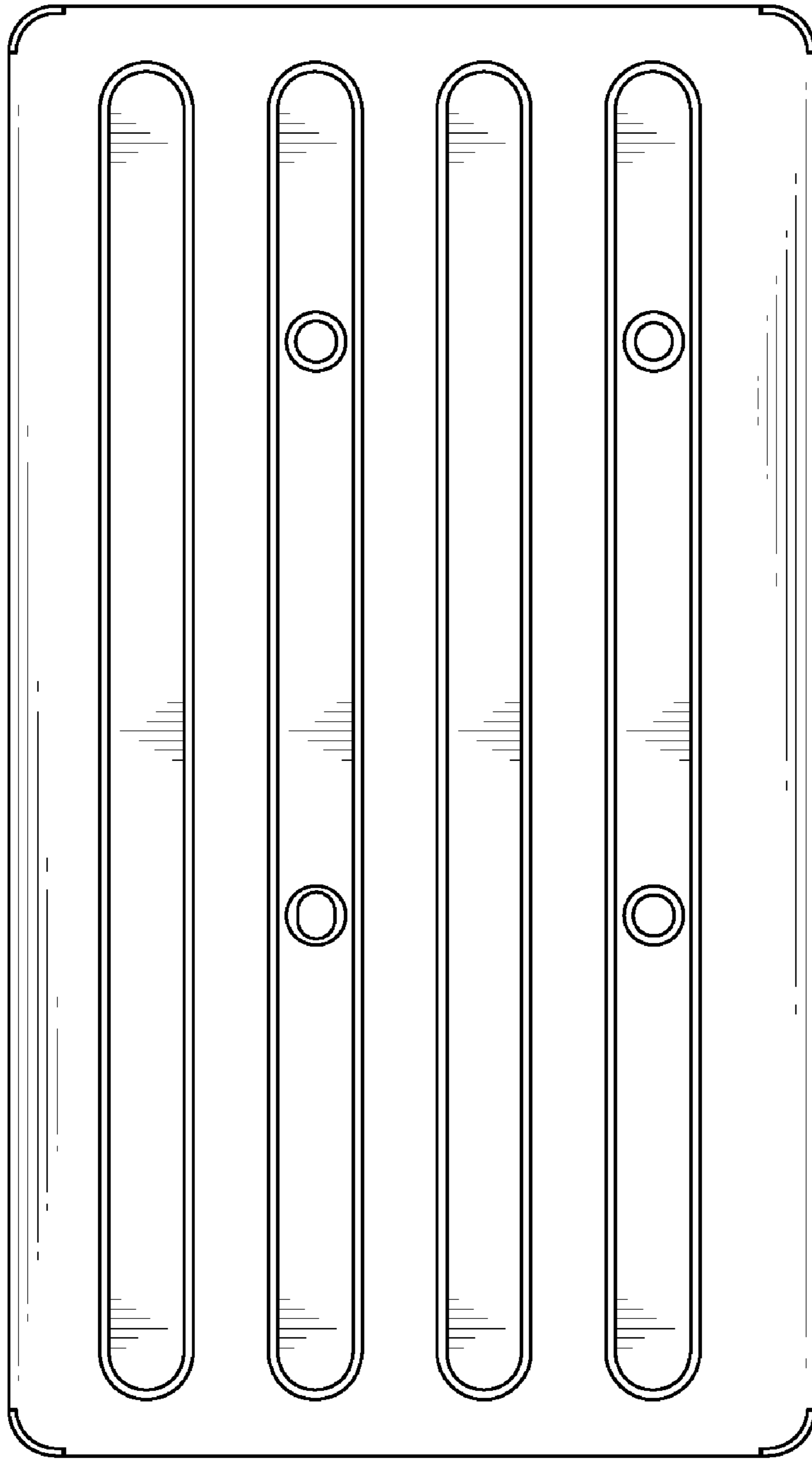


FIG. 6

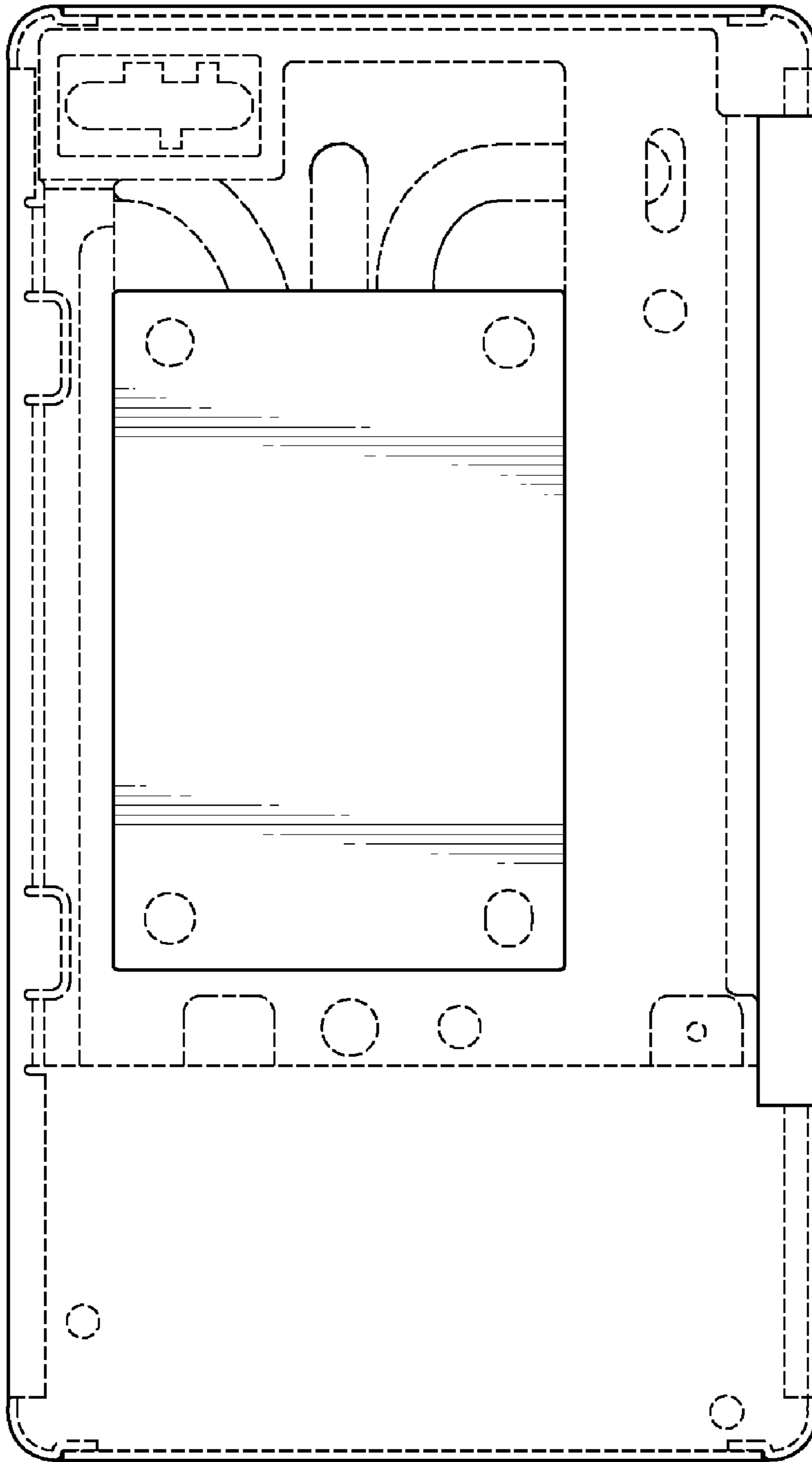


FIG. 7